CEP4060AR/CEB4060AR

March 1998

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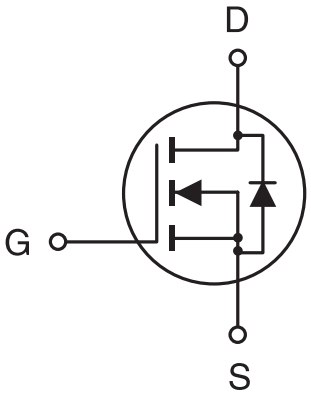
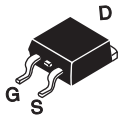
N-Channel Enhancement Mode Field Effect Transistor

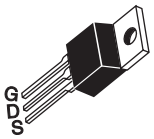
FEATURES

- 60V , 15A , $R_{DS(ON)}$=85mΩ @V_{GS}=10V.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handling capability.
- TO-220 & TO-263 package.





CEB SERIES
TO-263(DD-PAK)



CEP SERIES
TO-220

ABSOLUTE MAXIMUM RATINGS (Tc=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	15	A
-Pulsed	I_{DM}	45	A
Drain-Source Diode Forward Current	I_S	15	A
Maximum Power Dissipation @Tc=25°C	P_D	50	W
Derate above 25°C		0.35	W/°C
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to 175	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W

ELECTRICAL CHARACTERISTICS (Tc=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE AVALANCHE RATING [a]						
Single Pulse Drain-Source Avalanche Energy	E_{AS}	V_{DD}=25V, I_D=150A		430		mJ
Maximum Drain-Source Avalanche Current	I_{AS}	L=25μH		150		A
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V, I_D=250μA	60			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V, V_{GS}=0V			250	μA
Gate-Body Leakage	I_{GSS}	V_{GS}=±20V, V_{DS}=0V			±100	nA
ON CHARACTERISTICS [a]						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	2	2.8	4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=7.5A		66	85	mΩ
On-State Drain Current	$I_{D(ON)}$	V_{GS}=10V, V_{DS}=10V	15			A
Forward Transconductance	g_{FS}	V_{DS}=10V, I_D=7.5A		6		S
SWITCHING CHARACTERISTICS [b]						
Turn-On Delay Time	$t_{D(ON)}$	V_{DD}=30V, I_D=15A, V_{GS}=10V, V_{GEN}=25Ω		7	20	ns
Rise Time	t_r			65	100	ns
Turn-Off Delay Time	$t_{D(OFF)}$			15	30	ns
Fall Time	t_f			35	50	ns
Total Gate Charge	Q_g	V_{DS}=48V, I_D=15A, V_{GS}=10V		9	17	nC
Gate-Source Charge	Q_{gs}			2		nC
Gate-Drain Charge	Q_{gd}			4		nC

ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DYNAMIC CHARACTERISTICS[b]						
Input Capacitance	C_{ISS}	V_{DS} =25V, V_{GS} = 0V f =1.0MHz		292	400	pF
Output Capacitance	C_{OSS}			130	200	pF
Reverse Transfer Capacitance	C_{RSS}			36	50	pF
DRAIN-SOURCE DIODE CHARACTERISTICS [b]						
Diode Forward Voltage	V_{SD}	V_{GS} = 0V, Is =7.5A		0.8	1.3	V

Notes

a.Pulse Test:Pulse Width ≤300 μs, Duty Cycle ≤ 2%.

b.Guaranteed by design, not subject to production testing.

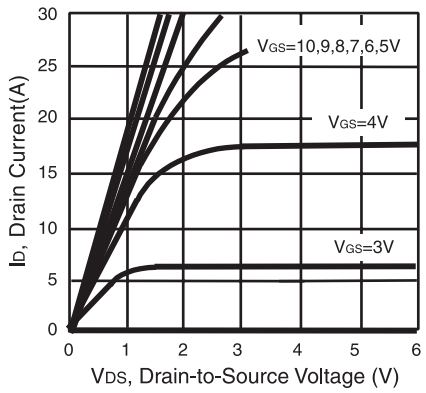


Figure 1. Output Characteristics

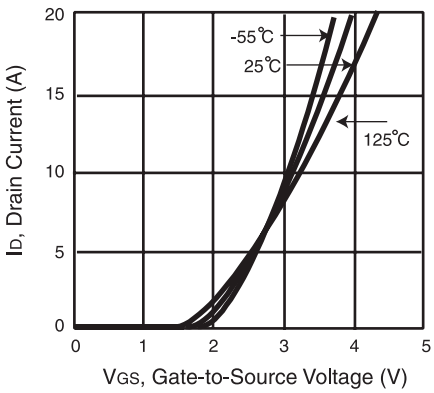


Figure 2. Transfer Characteristics

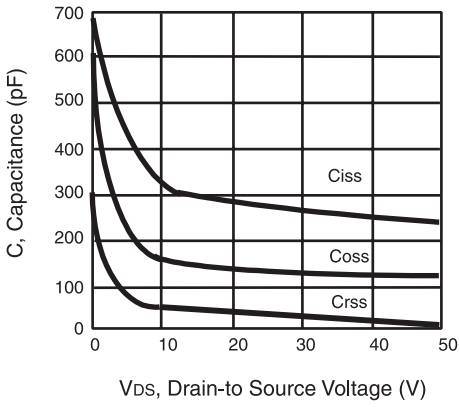


Figure 3. Capacitance

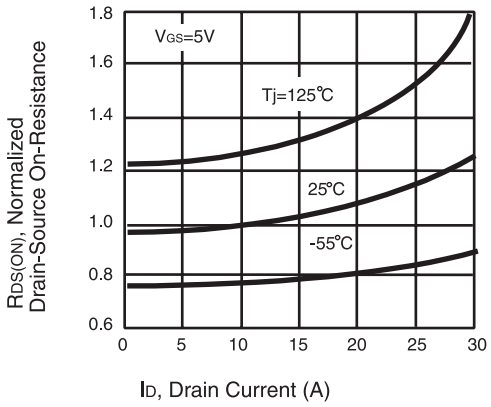


Figure 4. On-Resistance Variation with Drain Current and Temperature

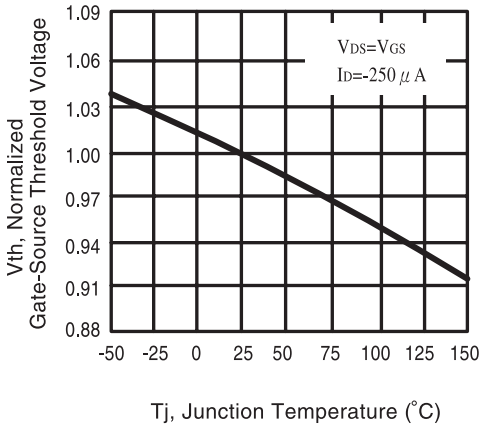


Figure 5. Gate Threshold Variation with Temperature

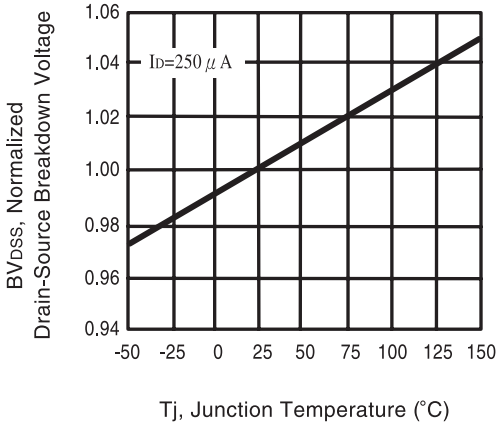


Figure 6. Breakdown Voltage Variation with Temperature

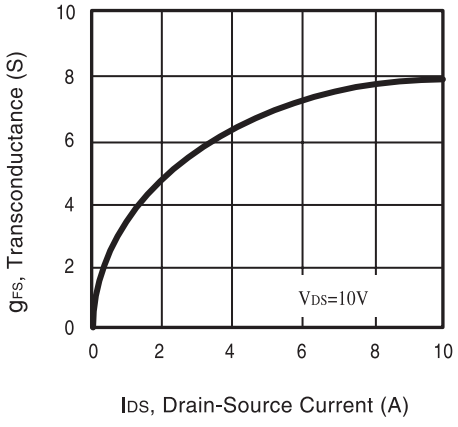


Figure 7. Transconductance Variation with Drain Current

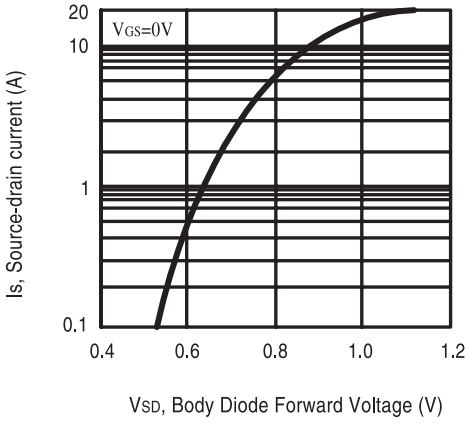


Figure 8. Body Diode Forward Voltage Variation with Source Current

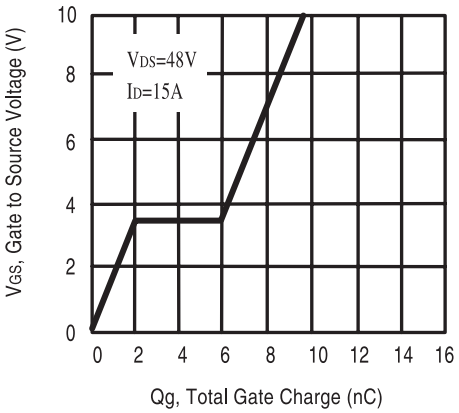


Figure 9. Gate Charge

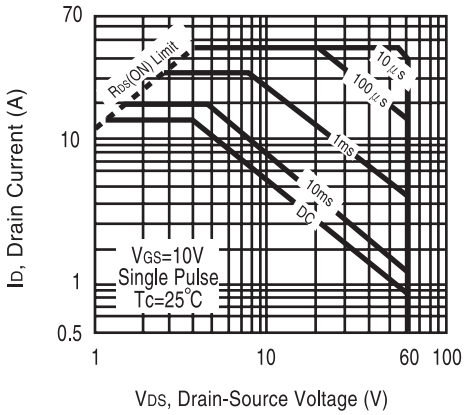


Figure 10. Maximum Safe Operating Area

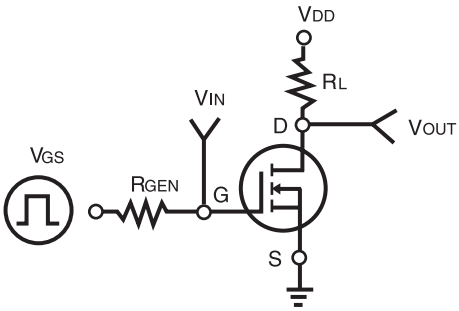


Figure 11. Switching Test Circuit

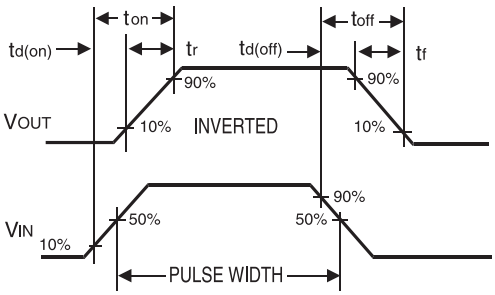


Figure 12. Switching Waveforms

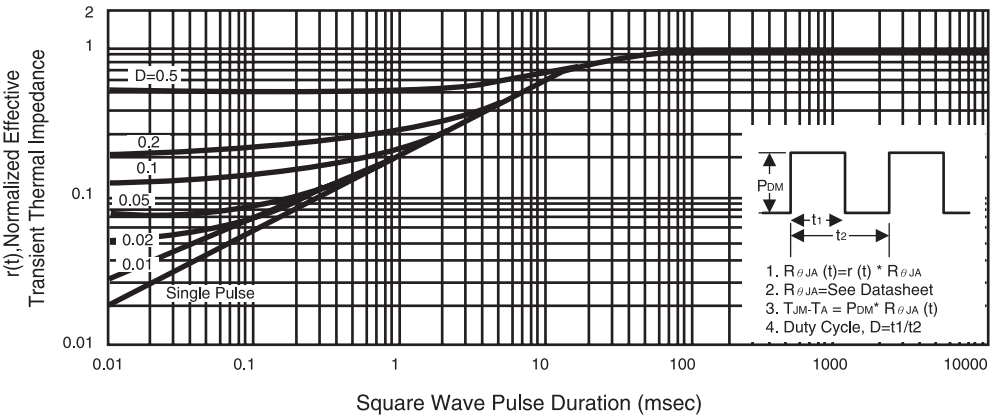


Figure 13. Normalized Thermal Transient Impedance Curve